

规格书编号 : HDBF07625A24SP01

SPEC NO : HDBF07625A24SP01

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_  
PRODUCT 产品: \_\_\_\_\_ SAW FILTER \_\_\_\_\_  
MODEL NO 型号: \_\_\_\_\_ HDBF07625A24 SMD-24 \_\_\_\_\_  
PREPARED 编制: \_\_\_\_\_ 俞虹 \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_ 邓攀 \_\_\_\_\_  
APPROVED 批准: \_\_\_\_\_ 倪山林 \_\_\_\_\_ DATE 日期: \_\_\_\_\_ 2009-04-21 \_\_\_\_\_

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited

## 更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark
2009.04.21	HDBF07625A 24SP01	HDBF07625A 24			Ver.01(Original)

## 1. SCOPE

This specification shall cover the characteristics of SAW filter with HDBF07625A24 used for the page system.

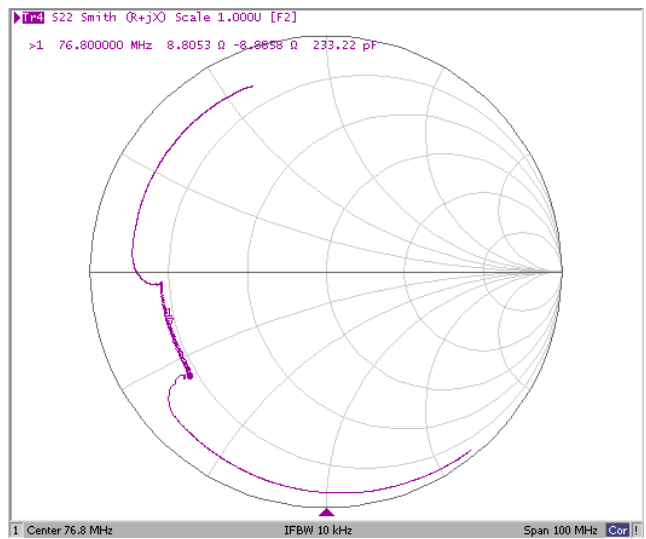
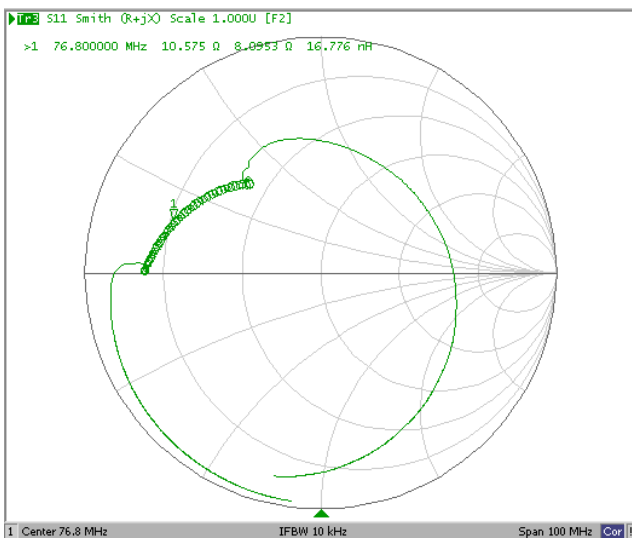
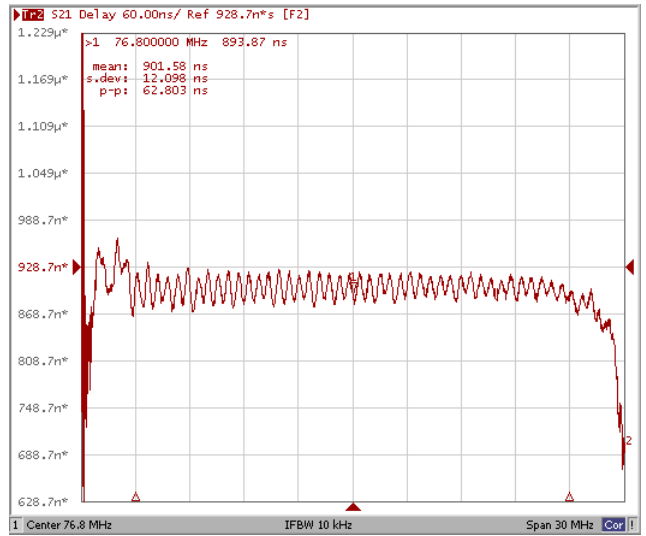
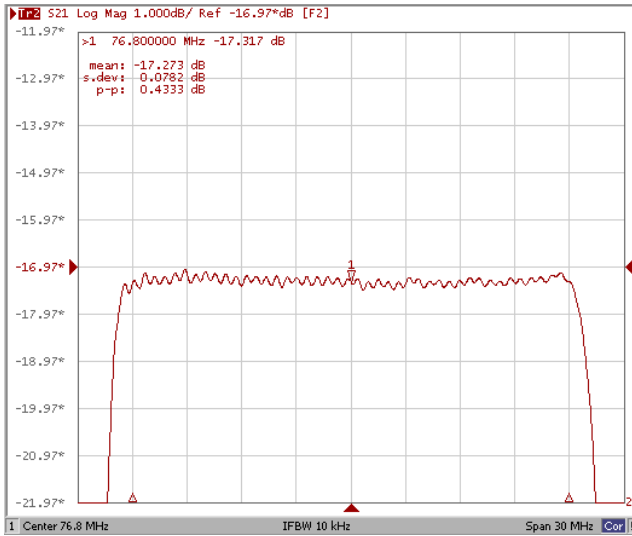
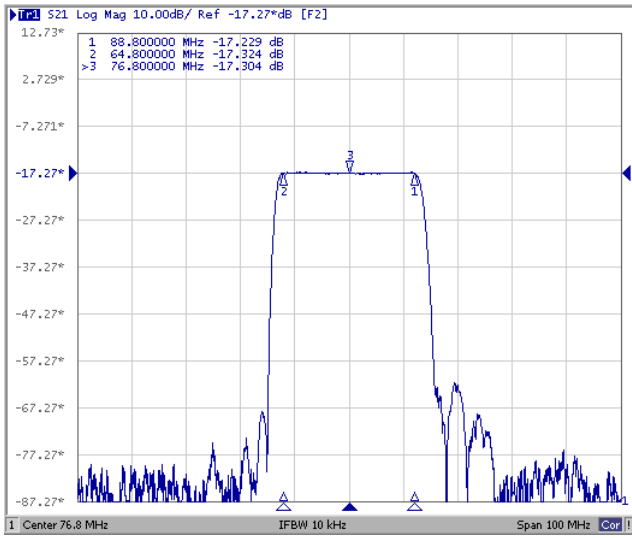
## 2. ELECTRICAL SPECIFICATION

Maximum incident power in passband	+10dBm
Max.DC voltage between any 2 terminals	30VDC
Storage temperature range	-40°C to +85°C
Operation temperature range	-40°C to +85°C

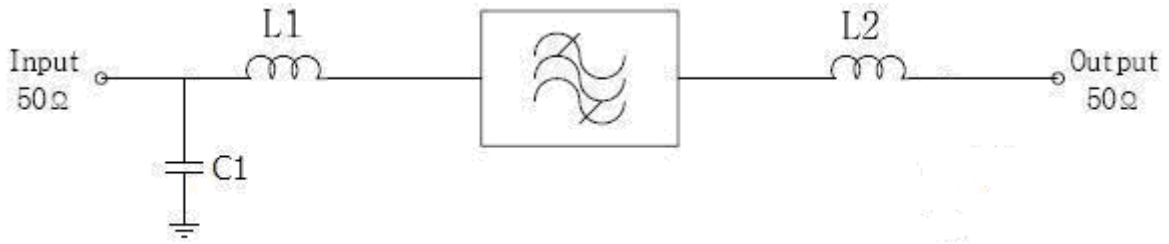
### Electronic Characteristics

Parameter	Min.	Typical.	Max.	Unit
Center Frequency	76.65	76.8	76.95	MHz
Insertion loss	-	17.3	20	dB
-1.2dB Bandwidth	24.8	25.7	-	MHz
-3dB Bandwidth	25	26.4		MHz
-10dB Bandwidth		27.77		MHz
-20dB Bandwidth		28.89		MHz
-35dB Bandwidth		30	31	MHz
Passband Variation		0.5	1.2	dB
Absolute Delay		0.9	1.2	us
Group delay Variation (F0 +/- 12MHz)		60	120	ns
Phase Linearity (F0 +/- 12MHz)		6	9	deg
Ultimate Rejection (Over F0 +/- 20MHz)	42	44		dB
Temperature Coefficient		-86		ppm/°C
Package Size	SMD 13.3*6.5			

**Typical frequency response**



**3. TEST CIRCUIT**

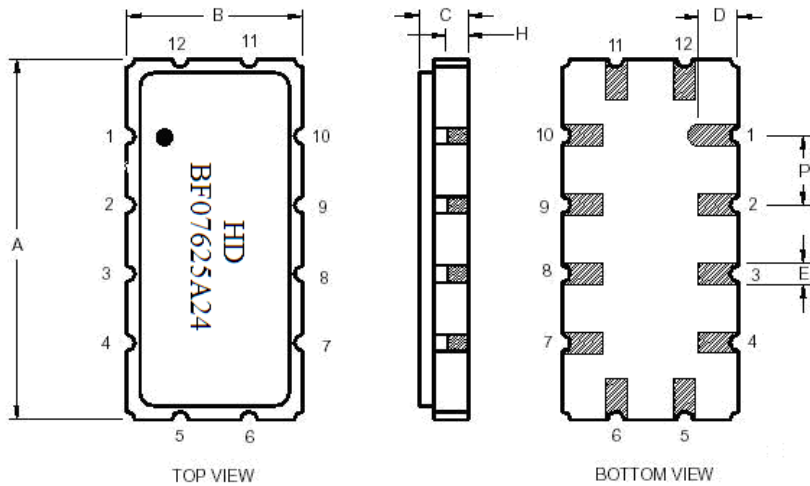


L1 = 68 nH , L2 = 56 nH

C1 = 51pF

\* Component values may change depending on board layout.

**4.DIMENSION**



Dimension	mm		
	min	typ	max
A	13.1	13.3	13.5
B	6.3	6.5	6.7
C	1.21	1.36	1.51
D		1.5	
E		0.8	
H	0.72	0.76	0.80
P		2.54	

Pin Configuration	
11	Input
5	Output
Other	Ground

## 5. ENVIRONMENTAL CHARACTERISTICS

### 5-1 Temperature cycling

Subject the device to a low temperature of  $-40^{\circ}\text{C}$  for 30 minutes. Following by a high temperature of  $+25^{\circ}\text{C}$  for 5 Minutes and a higher temperature of  $+85^{\circ}\text{C}$  for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in table 1.

### 5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at  $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for  $10 \pm 1$  sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in table 1.

### 5-3 Solderability

Submerge the device terminals into the solder bath at  $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in table 1.

### 5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in table 1.

### 5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in table 1.

## 6. REMARK

### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.